

Listing of Claims:

Claims 1 - 4 (Cancelled)

Claim 5. (Currently Amended) ~~A through hole conduction structure of a flexible multilayer circuit board according to claim 1;~~ A through hole conduction structure of a flexible multilayer circuit board, comprising: an internal layer circuit board having a wiring pattern and an external layer circuit board laminated on one side or both sides of said internal layer circuit board, a through hole plated conduction portion formed in said internal layer circuit board and said external layer circuit board, a surface protection layer formed on an external surface of the wiring pattern, said surface protection layer having a retreated portion which is outwardly retreated from the outside edge of the through hole, wherein a diameter of the through hole and a diameter of the outwardly retreated portion is about a 1 to 2.3 ratio

Claim 6. (Previously Presented) A through hole conduction structure of a flexible multilayer circuit board according to claim 5, wherein the diameter of the through hole is about 0.3 mm and the diameter of the outwardly retreated portion is about 0.7 mm.